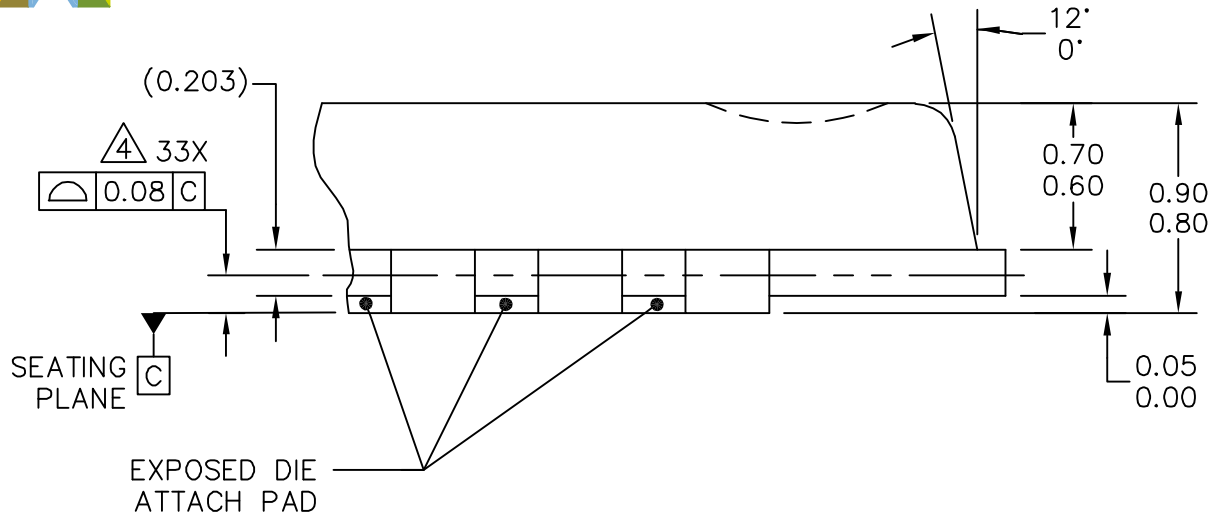


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TITLE: QFN (PUNCH), THERMALLY ENHANCED, 7 X 7 X 0.85, 0.65 PITCH, 32 TERMINAL	DOCUMENT NO: 98ARH99032A REV: H	
	STANDARD: JEDEC-MO-220 VKKC	
	SOT1579-1 05 FEB 2016	



DETAIL G
VIEW ROTATED 90° CW

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		STANDARD: JEDEC-MO-220 VKKC	
		SOT1579-1	05 FEB 2016



NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5–1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.

4. COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.

5. THIS DIMENSION APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM TERMINAL TIP.

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